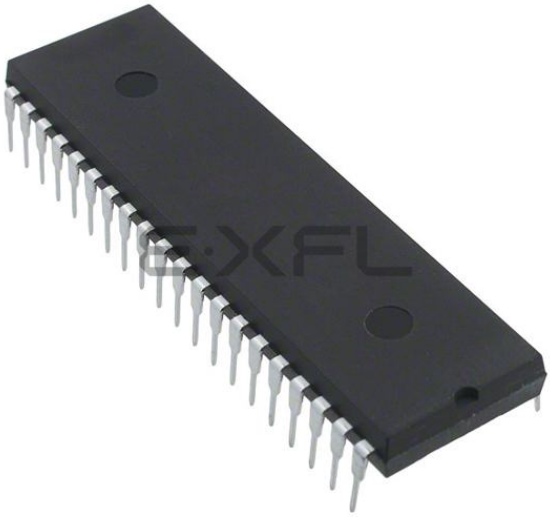

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1934-e-p

TABLE 2: 40/44-PIN SUMMARY(PIC16(L)F1934/7)

I/O	40-Pin PDIP	40-Pin UQFN	44-Pin TQFP	44-Pin QFN	ANSEL	A/D	Cap Sense	Comparator	SR Latch	Timers	CCP	EUSART	MSSP	LCD	Interrupt	Pull-up	Basic
RA0	2	17	19	19	Y	AN0	—	C12IN0-/ C2OUT(1)	SRNQ(1)	—	—	—	$\overline{SS}$(1)	SEG12	—	—	VCAP
RA1	3	18	20	20	Y	AN1	—	C12IN1-	—	—	—	—	—	SEG7	—	—	—
RA2	4	19	21	21	Y	AN2/ VREF-	—	C2IN+/ DACOUT	—	—	—	—	—	COM2	—	—	—
RA3	5	20	22	22	Y	AN3/ VREF+	—	C1IN+	—	—	—	—	—	SEG15	—	—	—
RA4	6	21	23	23	Y	—	CPS6	C1OUT	SRQ	T0CKI		—	—	SEG4	—	—	—
RA5	7	22	24	24	Y	AN4	CPS7	C2OUT(1)	SRNQ(1)	—	—	—	$\overline{SS}$(1)	SEG5	—	—	VCAP
RA6	14	29	31	33	—	—	—	—	—	—	—	—	—	SEG1	—	—	OSC2/ CLKOUT VCAP
RA7	13	28	30	32	—	—	—	—	—	—	—	—	—	SEG2	—	—	OSC1/ CLKIN
RB0	33	8	8	9	Y	AN12	CPS0	—	SRI	—	—	—	—	SEG0	INT/ IOC	Y	—
RB1	34	9	9	10	Y	AN10	CPS1	C12IN3-	—	—	—	—	—	VLCD1	IOC	Y	—
RB2	35	10	10	11	Y	AN8	CPS2	—	—	—	—	—	—	VLCD2	IOC	Y	—
RB3	36	11	11	12	Y	AN9	CPS3	C12IN2-	—	—	CCP2(1)/ P2A(1)	—	—	VLCD3	IOC	Y	—
RB4	37	12	14	14	Y	AN11	CPS4	—	—	—	—	—	—	COM0	IOC	Y	—
RB5	38	13	15	15	Y	AN13	CPS5	—	—	T1G(1)	CCP3(1)/ P3A(1)	—	—	COM1	IOC	Y	—
RB6	39	14	16	16	—	—	—	—	—	—	—	—	—	SEG14	IOC	Y	ICSPCLK/ ICDCLK
RB7	40	15	17	17	—	—	—	—	—	—	—	—	—	SEG13	IOC	Y	ICSPDAT/ ICDDAT
RC0	15	30	32	34	—	—	—	—	—	T1OSO/ T1CKI	P2B(1)	—	—	—	—	—	—
RC1	16	31	35	35	—	—	—	—	—	T1OSI	CCP2(1)/ P2A(1)	—	—	—	—	—	—
RC2	17	32	36	36	—	—	—	—	—	—	CCP1/ P1A	—	—	SEG3	—	—	—
RC3	18	33	37	37	—	—	—	—	—	—	—	—	SCK/SCL	SEG6	—	—	—
RC4	23	38	42	42	—	—	—	—	—	T1G(1)	—	—	SDI/SDA	SEG11	—	—	—
RC5	24	39	43	43	—	—	—	—	—	—	—	—	SDO	SEG10	—	—	—
RC6	25	40	44	44	—	—	—	—	—	—	—	TX/CK	—	SEG9	—	—	—
RC7	26	1	1	1	—	—	—	—	—	—	—	RX/DT	—	SEG8	—	—	—
RD0	19	34	38	38	Y	—	CPS8	—	—	—	—	—	—	COM3	—	—	—
RD1	20	35	39	39	Y	—	CPS9	—	—	—	CCP4	—	—	—	—	—	—
RD2	21	36	40	40	Y	—	CPS10	—	—	—	P2B(1)	—	—	—	—	—	—
RD3	22	37	41	41	Y	—	CPS11	—	—	—	P2C	—	—	SEG16	—	—	—
RD4	27	2	2	2	Y	—	CPS12	—	—	—	P2D	—	—	SEG17	—	—	—
RD5	28	3	3	3	Y	—	CPS13	—	—	—	P1B	—	—	SEG18	—	—	—
RD6	29	4	4	4	Y	—	CPS14	—	—	—	P1C	—	—	SEG19	—	—	—
RD7	30	5	5	5	Y	—	CPS15	—	—	—	P1D	—	—	SEG20	—	—	—
RE0	8	23	25	25	Y	AN5	—	—	—	—	CCP3(1) P3A(1)	—	—	SEG21	—	—	—
RE1	9	24	26	26	Y	AN6	—	—	—	—	P3B	—	—	SEG22	—	—	—
RE2	10	25	27	27	Y	AN7	—	—	—	—	CCP5	—	—	SEG23	—	—	—
RE3	1	16	18	18	—	—	—	—	—	—	—	—	—	—	—	Y	$\overline{MCLR}$/VPP
VDD	11, 32	7, 26	7, 28	7,8, 28	—	—	—	—	—	—	—	—	—	—	—	—	VDD
Vss	12, 31	6, 27	6, 29	6,30, 31	—	—	—	—	—	—	—	—	—	—	—	—	VSS

Note 1: Pin functions can be moved using the APFCON register.

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1.0 DEVICE OVERVIEW

The PIC16(L)F1934/6/7 are described within this data sheet. They are available in 28/40/44-pin packages. Figure 1-1 shows a block diagram of the PIC16(L)F1934/6/7 devices. Table 1-2 shows the pinout descriptions.

Reference Table 1-1 for peripherals available per device.

TABLE 1-1: DEVICE PERIPHERAL SUMMARY

Peripheral		PIC16F193X	PIC16LF193X
ADC		●	●
Capacitive Sensing Module		●	●
Digital-to-Analog Converter (DAC)		●	●
EUSART		●	●
Fixed Voltage Reference (FVR)		●	●
LCD		●	●
SR Latch		●	●
Temperature Indicator		●	●
Capture/Compare/PWM Modules			
	ECCP1	●	●
	ECCP2	●	●
	ECCP3	●	●
	CCP4	●	●
	CCP5	●	●
Comparators			
	C1	●	●
	C2	●	●
Operational Amplifiers			
	OPA1	●	●
	OPA2	●	●
Master Synchronous Serial Ports			
	MSSP1	●	●
Timers			
	Timer0	●	●
	Timer1	●	●
	Timer2	●	●
	Timer4	●	●
	Timer6	●	●

3.1.1.2 Indirect Read with FSR

The program memory can be accessed as data by setting bit 7 of the FSRxH register and reading the matching INDFx register. The MOVIW instruction will place the lower 8 bits of the addressed word in the W register. Writes to the program memory cannot be performed via the INDF registers. Instructions that access the program memory via the FSR require one extra instruction cycle to complete. Example 3-2 demonstrates accessing the program memory via an FSR.

The HIGH directive will set bit<7> if a label points to a location in program memory.

EXAMPLE 3-2: ACCESSING PROGRAM MEMORY VIA FSR

```
constants
    RETLW DATA0        ;Index0 data
    RETLW DATA1        ;Index1 data
    RETLW DATA2
    RETLW DATA3
my_function
    ;… LOTS OF CODE…
    MOVLW  LOW constants
    MOVWF  FSR1L
    MOVLW  HIGH constants
    MOVWF  FSR1H
    MOVIW  0[FSR1]
;THE PROGRAM MEMORY IS IN W
```

3.2 Data Memory Organization

The data memory is partitioned in 32 memory banks with 128 bytes in a bank. Each bank consists of (Figure 3-3):

- 12 core registers
- 20 Special Function Registers (SFR)
- Up to 80 bytes of General Purpose RAM (GPR)
- 16 bytes of common RAM

The active bank is selected by writing the bank number into the Bank Select Register (BSR). Unimplemented memory will read as '0'. All data memory can be accessed either directly (via instructions that use the file registers) or indirectly via the two File Select Registers (FSR). See **Section 3.5 "Indirect Addressing"** for more information.

3.2.1 CORE REGISTERS

The core registers contain the registers that directly affect the basic operation of the PIC16(L)F1934/6/7. These registers are listed below:

- INDF0
- INDF1
- PCL
- STATUS
- FSR0 Low
- FSR0 High
- FSR1 Low
- FSR1 High
- BSR
- WREG
- PCLATH
- INTCON

Note:	The core registers are the first 12 addresses of every data memory bank.

TABLE 3-12: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 15 (Continued)											
7A6h	LCDDATA6	SEG7 COM2	SEG6 COM2	SEG5 COM2	SEG4 COM2	SEG3 COM2	SEG2 COM2	SEG1 COM2	SEG0 COM2	xxxx xxxx	uuuu uuuu
7A7h	LCDDATA7	SEG15 COM2	SEG14 COM2	SEG13 COM2	SEG12 COM2	SEG11 COM2	SEG10 COM2	SEG9 COM2	SEG8 COM2	xxxx xxxx	uuuu uuuu
7A8h	LCDDATA8(3)	SEG23 COM2	SEG22 COM2	SEG21 COM2	SEG20 COM2	SEG19 COM2	SEG18 COM2	SEG17 COM2	SEG16 COM2	xxxx xxxx	uuuu uuuu
7A9h	LCDDATA9	SEG7 COM3	SEG6 COM3	SEG5 COM3	SEG4 COM3	SEG3 COM3	SEG2 COM3	SEG1 COM3	SEG0 COM3	xxxx xxxx	uuuu uuuu
7AAh	LCDDATA10	SEG15 COM3	SEG14 COM3	SEG13 COM3	SEG12 COM3	SEG11 COM3	SEG10 COM3	SEG9 COM3	SEG8 COM3	xxxx xxxx	uuuu uuuu
7ABh	LCDDATA11(3)	SEG23 COM3	SEG22 COM3	SEG21 COM3	SEG20 COM3	SEG19 COM3	SEG18 COM3	SEG17 COM3	SEG16 COM3	xxxx xxxx	uuuu uuuu
7ACh — 7EFh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<14:8>, whose contents are transferred to the upper byte of the program counter.

2: These registers can be addressed from any bank.

3: These registers/bits are not implemented on PIC16(L)F1936 devices, read as '0'.

4: Unimplemented, read as '1'.

6.0 RESETS

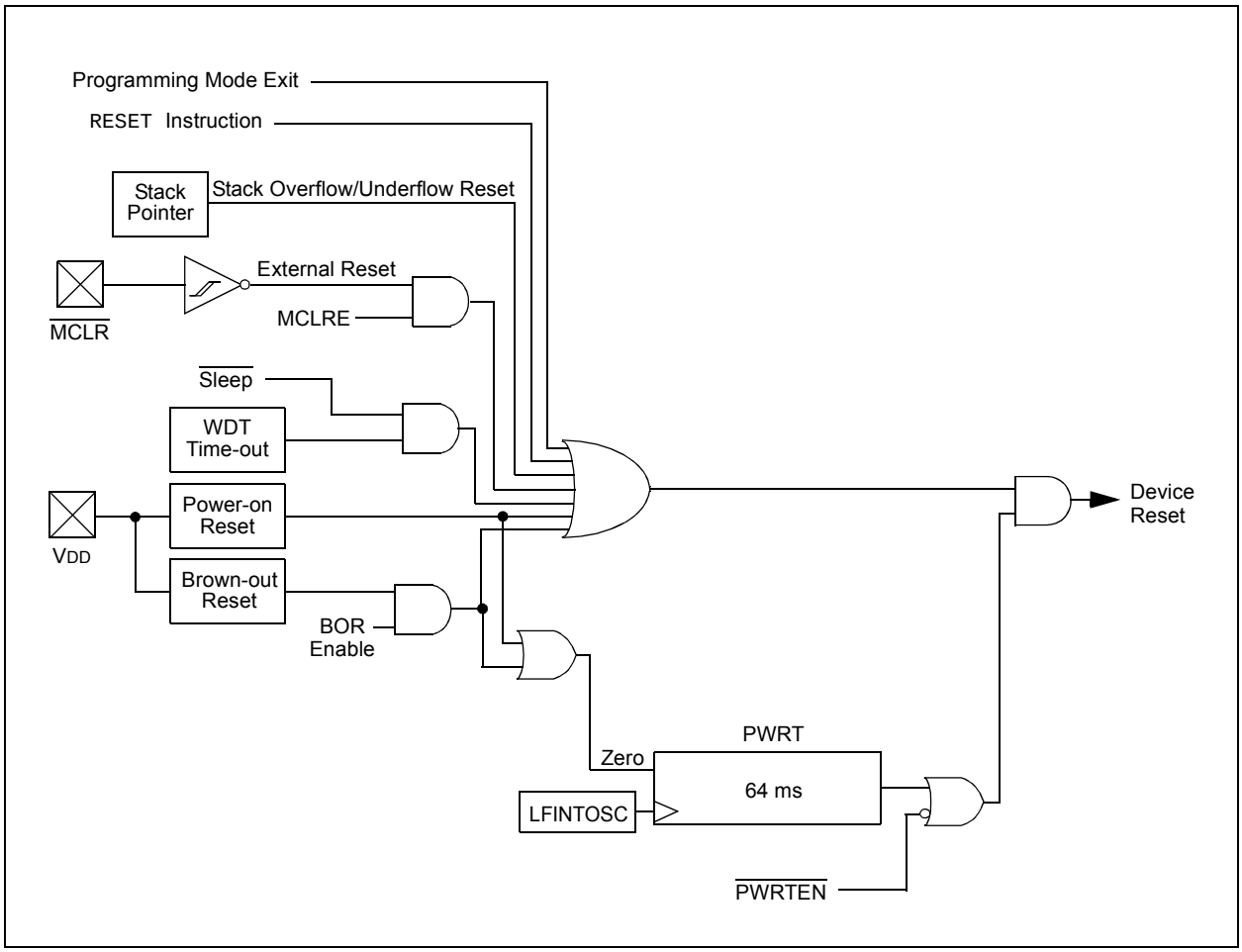
There are multiple ways to reset this device:

- Power-on Reset (POR)
- Brown-out Reset (BOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional power-up timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 6-1.

FIGURE 6-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 12.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are 17 channel selections available:

- AN<13:0> pins
- Temperature Indicator
- DAC Output
- FVR (Fixed Voltage Reference) Output

Refer to **Section 16.0 "Temperature Indicator Module"**, **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on these channel selections.

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 15.2 "ADC Operation"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADPREF bits of the ADCON1 register provides control of the positive voltage reference. The positive voltage reference can be:

- VREF+ pin
- VDD
- FVR 2.048V
- FVR 4.096V (Not available on LF devices)

The ADNREF bits of the ADCON1 register provides control of the negative voltage reference. The negative voltage reference can be:

- VREF- pin
- VSS

See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more details on the fixed voltage reference.

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

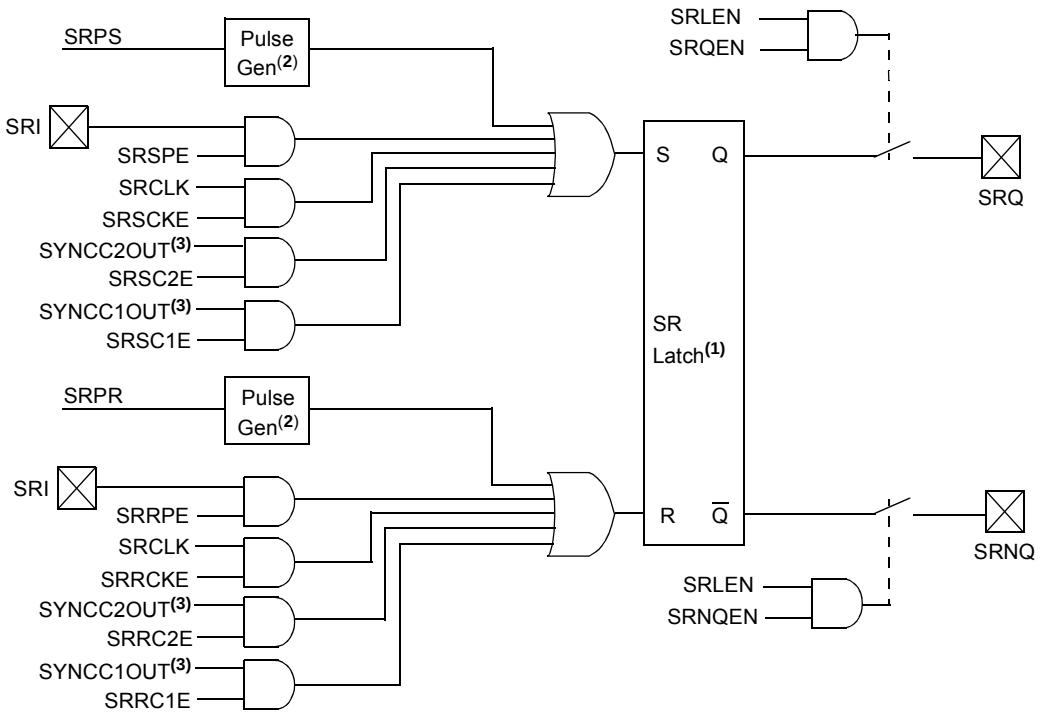
- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 10-bit conversion requires 11.5 TAD periods as shown in Figure 15-2.

For correct conversion, the appropriate TAD specification must be met. Refer to the A/D conversion requirements in the applicable Electrical Specifications Chapter for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

FIGURE 19-1: SR LATCH SIMPLIFIED BLOCK DIAGRAM



Note 1: If R = 1 and S = 1 simultaneously, Q = 0, $\overline{Q}$ = 1
2: Pulse generator causes a 1 Q-state pulse width.
3: Name denotes the connection point at the comparator output.

23.1 Capture Mode

The Capture mode function described in this section is available and identical for CCP modules ECCP1, ECCP2, ECCP3, CCP4 and CCP5.

Capture mode makes use of the 16-bit Timer1 resource. When an event occurs on the CCPx pin, the 16-bit CCPRxH:CCPRxL register pair captures and stores the 16-bit value of the TMR1H:TMR1L register pair, respectively. An event is defined as one of the following and is configured by the CCPxM<3:0> bits of the CCPxCON register:

- Every falling edge
- Every rising edge
- Every 4th rising edge
- Every 16th rising edge

When a capture is made, the Interrupt Request Flag bit CCPxIF of the PIRx register is set. The interrupt flag must be cleared in software. If another capture occurs before the value in the CCPRxH, CCPRxL register pair is read, the old captured value is overwritten by the new captured value.

Figure 23-1 shows a simplified diagram of the Capture operation.

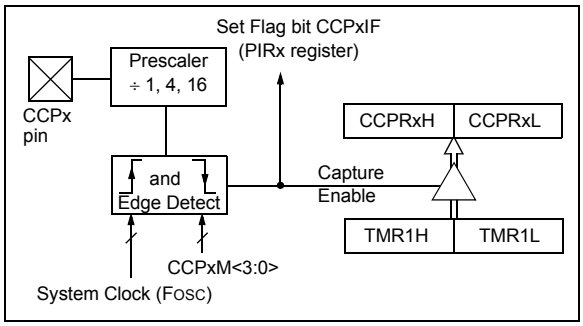
23.1.1 CCP PIN CONFIGURATION

In Capture mode, the CCPx pin should be configured as an input by setting the associated TRIS control bit.

Also, the CCPx pin function can be moved to alternative pins using the APFCON register. Refer to **Section 12.1 "Alternate Pin Function"** for more details.

Note:	If the CCPx pin is configured as an output, a write to the port can cause a capture condition.

FIGURE 23-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



23.1.2 TIMER1 MODE RESOURCE

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

See **Section 21.0 "Timer1 Module with Gate Control"** for more information on configuring Timer1.

23.1.3 SOFTWARE INTERRUPT MODE

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep the CCPxIE interrupt enable bit of the PIEx register clear to avoid false interrupts. Additionally, the user should clear the CCPxIF interrupt flag bit of the PIRx register following any change in Operating mode.

Note:	Clocking Timer1 from the system clock (FOSC) should not be used in Capture mode. In order for Capture mode to recognize the trigger event on the CCPx pin, Timer1 must be clocked from the instruction clock (FOSC/4) or from an external clock source.

23.1.4 CCP PRESCALER

There are four prescaler settings specified by the CCPxM<3:0> bits of the CCPxCON register. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. Any Reset will clear the prescaler counter.

Switching from one capture prescaler to another does not clear the prescaler and may generate a false interrupt. To avoid this unexpected operation, turn the module off by clearing the CCPxCON register before changing the prescaler. Example 23-1 demonstrates the code to perform this function.

EXAMPLE 23-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
BANKSEL CCPxCON     ;Set Bank bits to point
                    ;to CCPxCON
CLRF    CCPxCON     ;Turn CCP module off
MOVLW   NEW_CAPT_PS;Load the W reg with
                    ;the new prescaler
                    ;move value and CCP ON
MOVWF   CCPxCON     ;Load CCPxCON with this
                    ;value
```

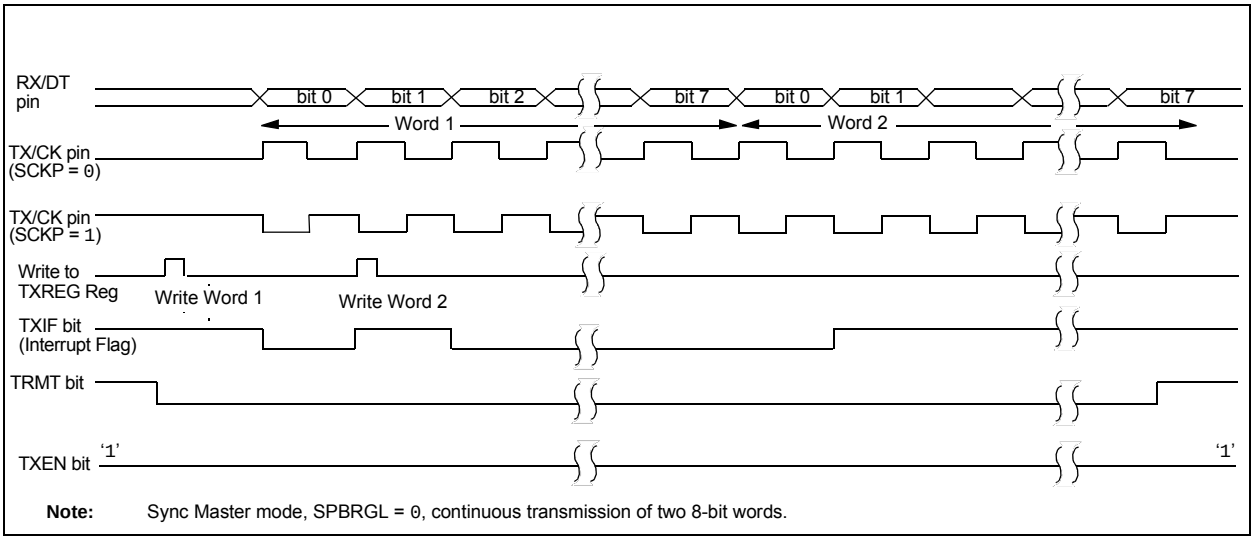
23.1.5 CAPTURE DURING SLEEP

Capture mode depends upon the Timer1 module for proper operation. There are two options for driving the Timer1 module in Capture mode. It can be driven by the instruction clock (FOSC/4), or by an external clock source.

When Timer1 is clocked by FOSC/4, Timer1 will not increment during Sleep. When the device wakes from Sleep, Timer1 will continue from its previous state.

Capture mode will operate during Sleep when Timer1 is clocked by an external clock source.

FIGURE 25-10: SYNCHRONOUS TRANSMISSION



Note: Sync Master mode, SPBRGL = 0, continuous transmission of two 8-bit words.

FIGURE 25-11: SYNCHRONOUS TRANSMISSION (THROUGH TXEN)

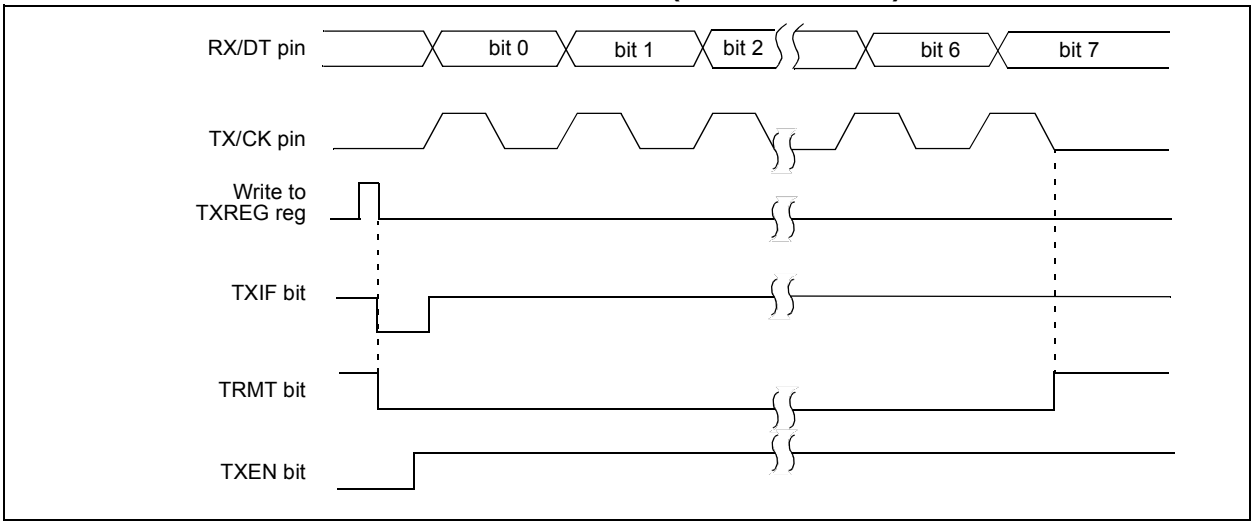


TABLE 25-7: SUMMARY OF REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	302
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	98
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	99
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	102
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	301
SPBRGL	BRG<7:0>								303*
SPBRGH	BRG<15:8>								303*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	142
TXREG	EUSART Transmit Data Register								293*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	300

Legend: — = unimplemented read as '0'. Shaded cells are not used for synchronous master transmission.

* Page provides register information.

REGISTER 27-2: LCDPS: LCD PHASE REGISTER

R/W-0/0	R/W-0/0	R-0/0	R-0/0	R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1
WFT	BIASMD	LCDA	WA	LP<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	C = Only clearable bit

bit 7 **WFT:** Waveform Type bit
1 = Type-B phase changes on each frame boundary
0 = Type-A phase changes within each common type

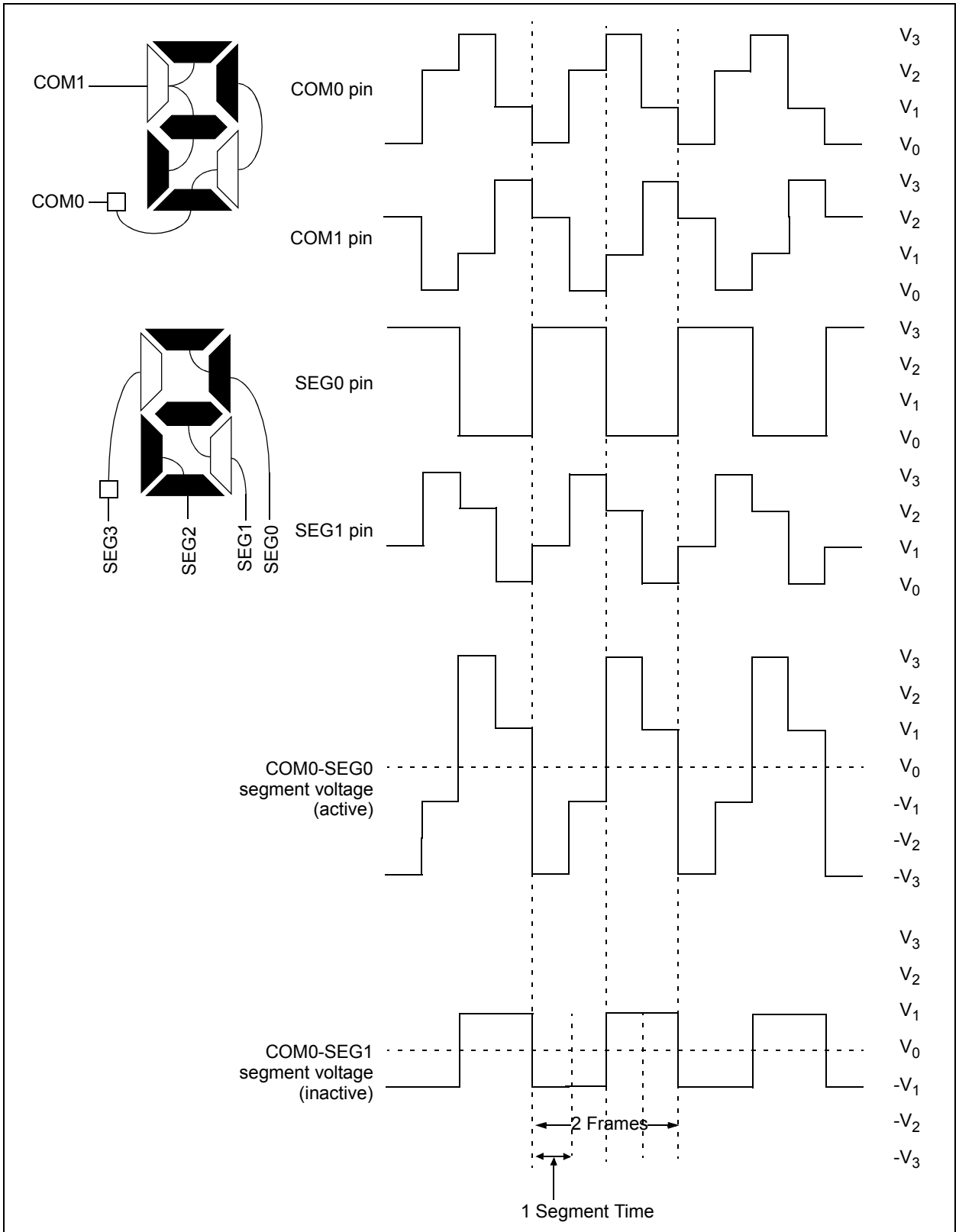
bit 6 **BIASMD:** Bias Mode Select bit
When LMUX<1:0> = 00:
0 = Static Bias mode (do not set this bit to '1')
When LMUX<1:0> = 01:
1 = 1/2 Bias mode
0 = 1/3 Bias mode
When LMUX<1:0> = 10:
1 = 1/2 Bias mode
0 = 1/3 Bias mode
When LMUX<1:0> = 11:
0 = 1/3 Bias mode (do not set this bit to '1')

bit 5 **LCDA:** LCD Active Status bit
1 = LCD Driver module is active
0 = LCD Driver module is inactive

bit 4 **WA:** LCD Write Allow Status bit
1 = Writing to the LCDDATAn registers is allowed
0 = Writing to the LCDDATAn registers is not allowed

bit 3-0 **LP<3:0>:** LCD Prescaler Selection bits
1111 = 1:16
1110 = 1:15
1101 = 1:14
1100 = 1:13
1011 = 1:12
1010 = 1:11
1001 = 1:10
1000 = 1:9
0111 = 1:8
0110 = 1:7
0101 = 1:6
0100 = 1:5
0011 = 1:4
0010 = 1:3
0001 = 1:2
0000 = 1:1

FIGURE 27-12: TYPE-B WAVEFORMS IN 1/2 MUX, 1/3 BIAS DRIVE

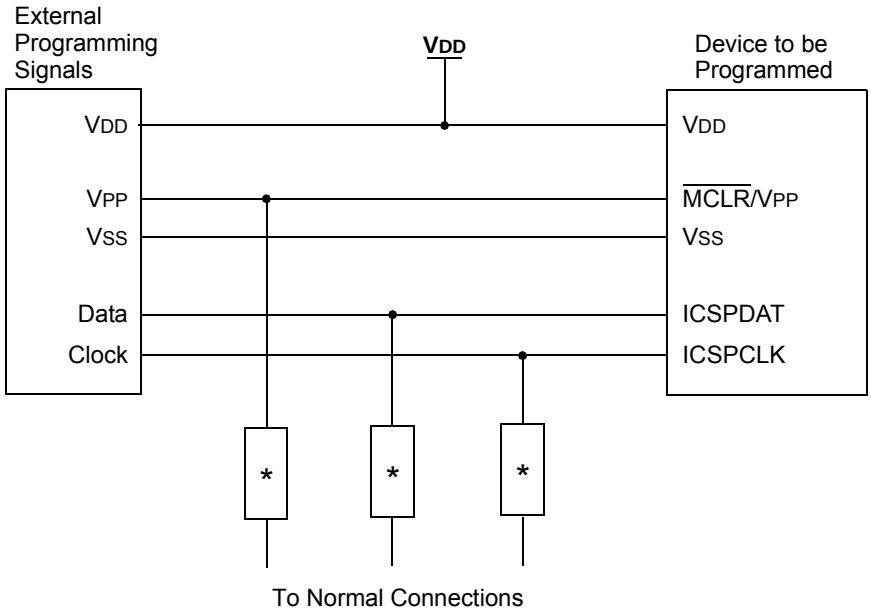


Note: 1 Frame = 2 single segment times.

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 28-4 for more information.

FIGURE 28-4: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



* Isolation devices (as required).

MOVWI **Move W to INDFn**

Syntax: [*label*] MOVWI ++FSRn
[*label*] MOVWI --FSRn
[*label*] MOVWI FSRn++
[*label*] MOVWI FSRn--
[*label*] MOVWI k[FSRn]

Operands: $n \in [0,1]$
$mm \in [00, 01, 10, 11]$
$-32 \leq k \leq 31$

Operation: $W \rightarrow INDFn$
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)

Unchanged

Status Affected: None

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap around.

The increment/decrement operation on FSRn WILL NOT affect any Status bits.

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Description: No operation.

Words: 1

Cycles: 1

Example:
```
NOP
```

OPTION **Load OPTION_REG Register with W**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION_REG

Status Affected: None

Description: Move data from W register to OPTION_REG register.

Words: 1

Cycles: 1

Example:
```
OPTION
```
Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

RESET **Software Reset**

Syntax: [*label*] RESET

Operands: None

Operation: Execute a device Reset. Resets the nRI flag of the PCON register.

Status Affected: None

Description: This instruction provides a way to execute a hardware Reset by software.

30.1 DC Characteristics: PIC16(L)F1934/6/7-I/E (Industrial, Extended)

PIC16LF1934/36/37			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F1934/36/37			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC16LF1934/36/37	1.8 2.3	— —	3.6 3.6	V V	FOSC ≤ 16 MHz: FOSC ≤ 32 MHz (**Note 2**)
D001		PIC16F1934/36/37	1.8 2.3	— —	5.5 5.5	V V	FOSC ≤ 16 MHz: FOSC ≤ 32 MHz (**Note 2**)
D002*	VDR	**RAM Data Retention Voltage(1)**					
		PIC16LF1934/36/37	1.5	—	—	V	Device in Sleep mode
D002*		PIC16F1934/36/37	1.7	—	—	V	Device in Sleep mode
	VPOR*	**Power-on Reset Release Voltage**	—	1.6	—	V	
	VPORR*	**Power-on Reset Rearm Voltage**					
		PIC16LF1934/36/37	—	0.8	—	V	Device in Sleep mode
		PIC16F1934/36/37	—	1.7	—	V	Device in Sleep mode
D003	VADFVR	**Fixed Voltage Reference Voltage for ADC**	-8		6	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V
D003A	VCDAFVR	**Fixed Voltage Reference Voltage for Comparator and DAC**	-11		7	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V
D003B	VLCDFVR	**Fixed Voltage Reference Voltage for LCD Bias**	-11	—	10	%	3.072V, VDD ≥ 3.6V
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 6.1 "Power-on Reset (POR)"** for details.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: PLL required for 32 MHz operation.

30.7 Timing Parameter Symbology

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

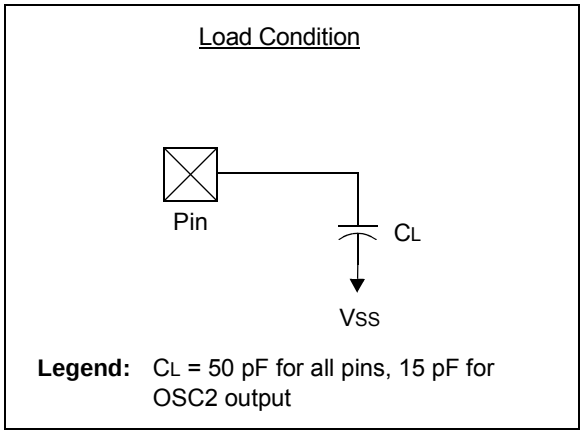
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 30-5: LOAD CONDITIONS



Legend: CL = 50 pF for all pins, 15 pF for OSC2 output

FIGURE 30-7: CLKOUT AND I/O TIMING

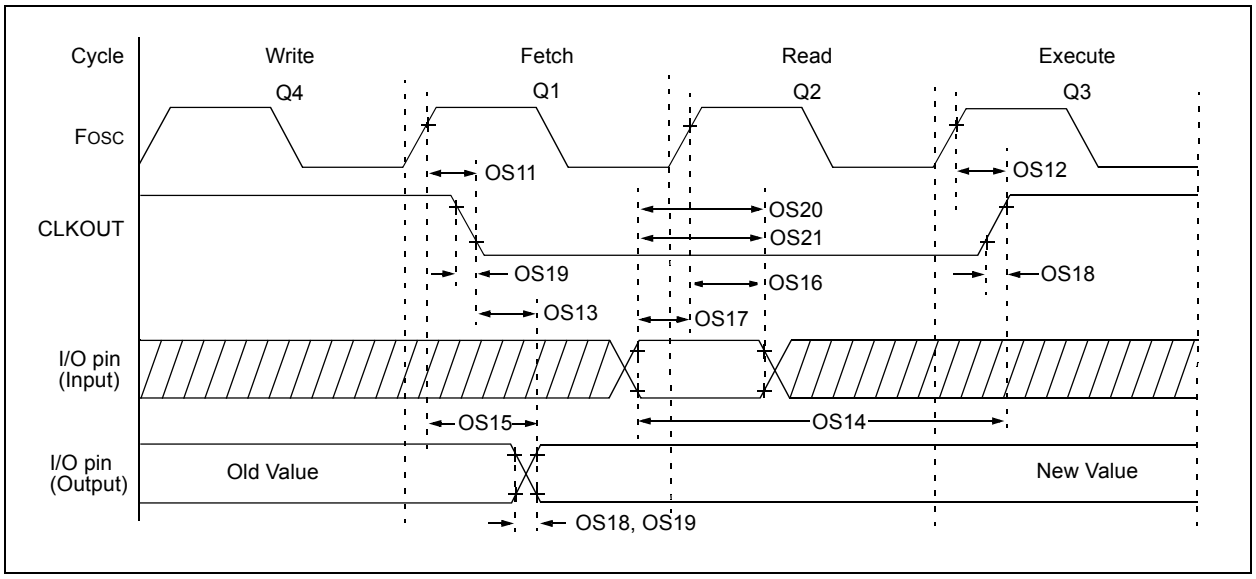


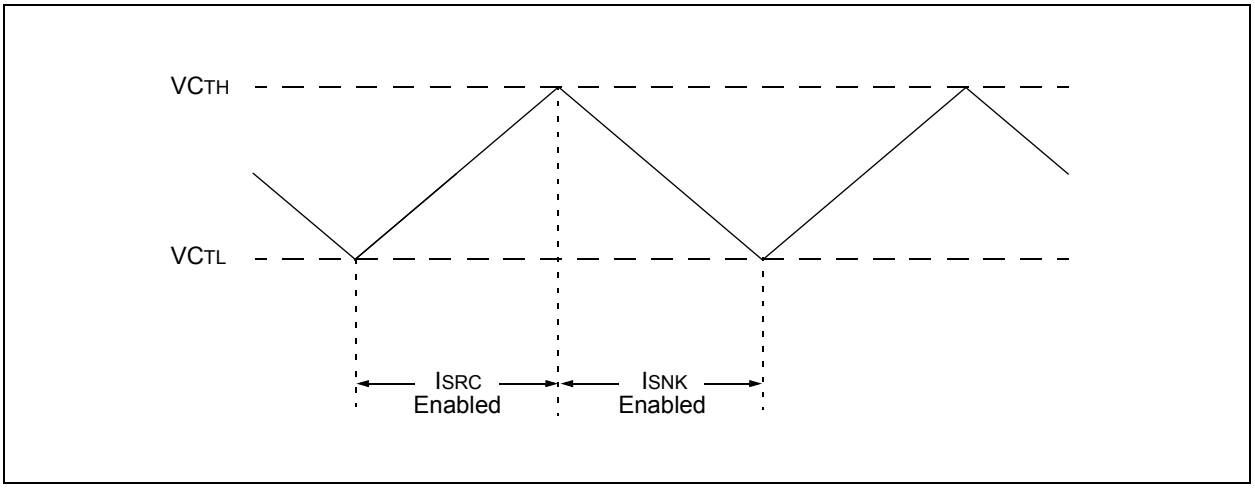
TABLE 30-17: CAP SENSE OSCILLATOR SPECIFICATIONS

Param. No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
CS01	ISRC	Current Source	High	-3	-8	-15	μA	
			Medium	-0.8	-1.5	-3	μA	
			Low	-0.1	-0.3	-0.4	μA	
CS02	ISNK	Current Sink	High	2.5	7.5	14	μA	
			Medium	0.6	1.5	2.9	μA	
			Low	0.1	0.25	0.6	μA	
CS03	VCTH	Cap Threshold		—	0.8	—	mV	
CS04	VCTL	Cap Threshold		—	0.4	—	mV	
CS05	VCHYST	Cap Hysteresis (VCTH-VCTL)	High Medium Low	350 250 175	525 375 300	725 500 425	mV mV mV	

* These parameters are characterized but not tested.

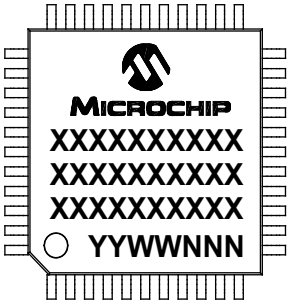
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 30-22: CAP SENSE OSCILLATOR

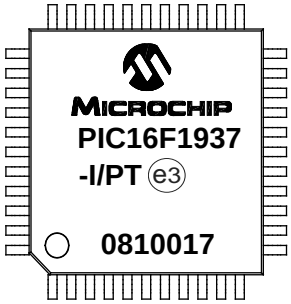


Package Marking Information (Continued)

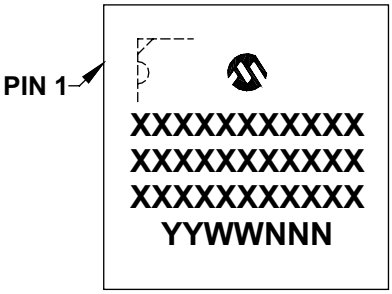
44-Lead TQFP (10x10x1 mm)



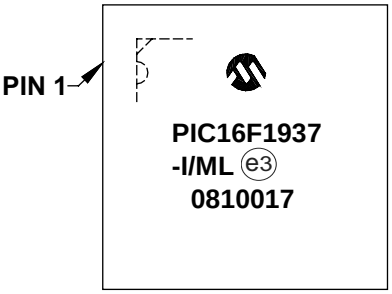
Example



44-Lead QFN (8x8x0.9 mm)

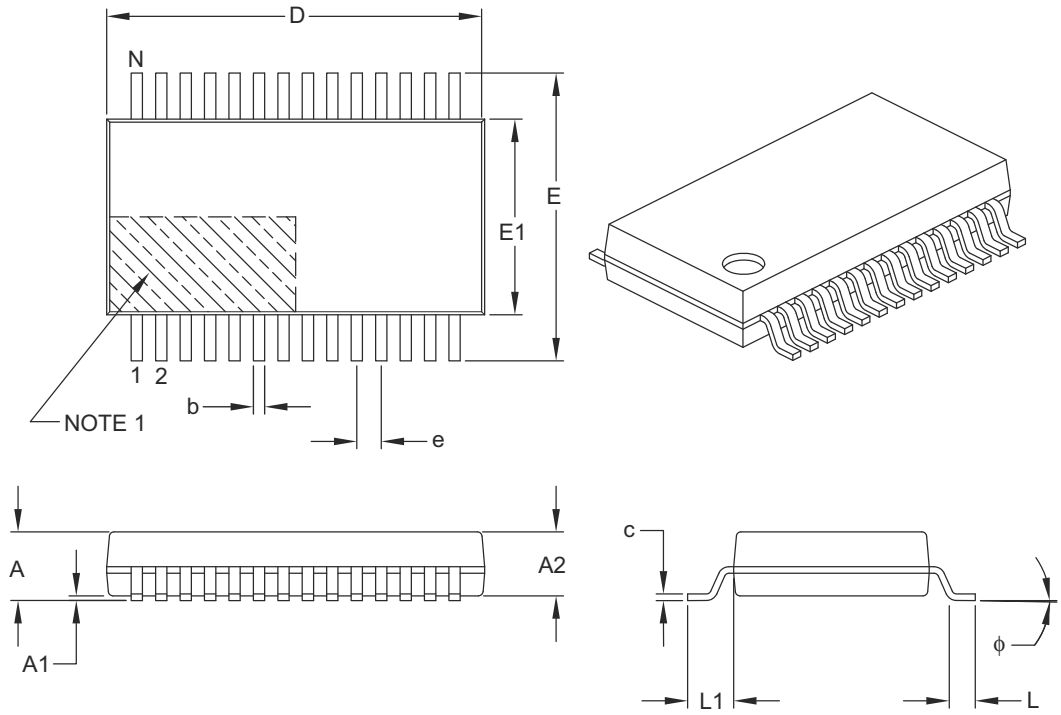


Example



28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B